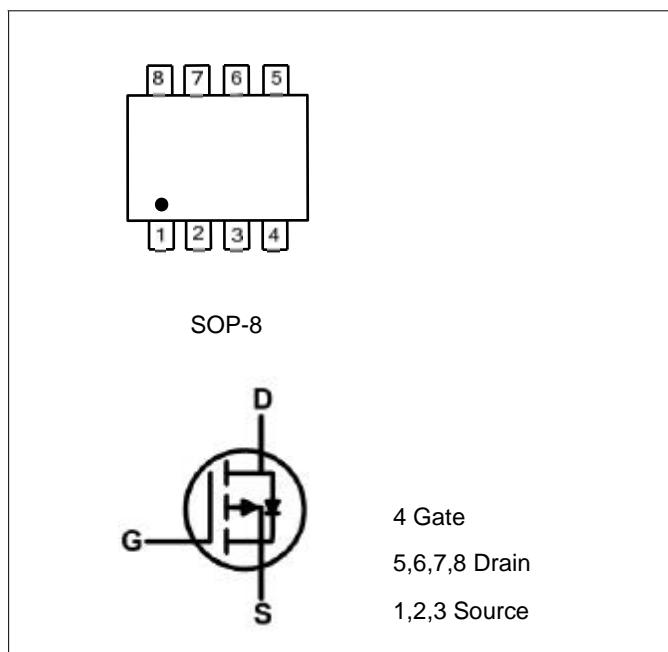


FH4407

-30V P-Channel Power MOSFET



BVDSS	RDS(on)	ID
-30V	15mΩ	-11.5A

General Features

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline

Absolute Maximum Rating

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-11.5	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -10V ¹	-9	A
I _{DM}	Pulsed Drain Current ²	-46	A
EAS	Single Pulse Avalanche Energy ³	125	mJ
I _{AS}	Avalanche Current	-50	A
P _D @T _A =25°C	Total Power Dissipation ⁴	1.5	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	75	°C/W
	Thermal Resistance Junction-Ambient ¹ (t≤10s)	---	40	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	24	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $I_{\text{D}}=-1\text{mA}$	---	-0.023	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-10\text{A}$	---	---	15	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-10\text{A}$	---	---	25	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=-250\mu\text{A}$	-1.0	---	-2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	4.6	---	$\text{mV}/^\circ\text{C}$
I_{DS}	Drain-Source Leakage Current	$V_{\text{DS}}=-24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	uA
		$V_{\text{DS}}=-24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$, $I_{\text{D}}=-10\text{A}$	---	24	---	S
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	9	---	Ω
Q_g	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-10\text{A}$	---	20	---	nC
Q_{gs}	Gate-Source Charge		---	5.1	---	
Q_{gd}	Gate-Drain Charge		---	7.3	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=-15\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_g=3.3\Omega$	---	33.8	---	ns
T_r	Rise Time		---	35.8	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	72.8	---	
T_f	Fall Time		---	10.6	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2215	---	pF
C_{oss}	Output Capacitance		---	310	---	
C_{rss}	Reverse Transfer Capacitance		---	237	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	-11.5	A
I_{SM}	Pulsed Source Current ^{2,5}		---	---	-46	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_{\text{S}}=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=-25\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=-50\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

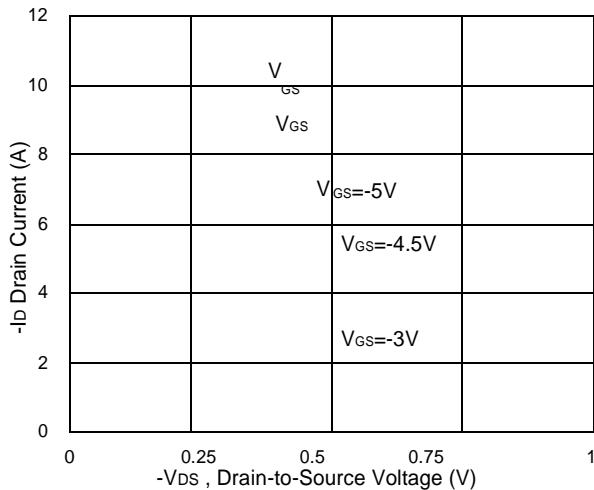


Fig.1 Typical Output Characteristics

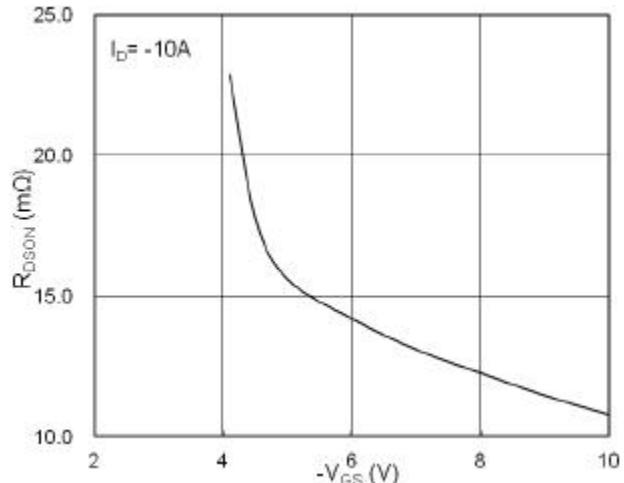


Fig.2 On-Resistance vs. G-S Voltage

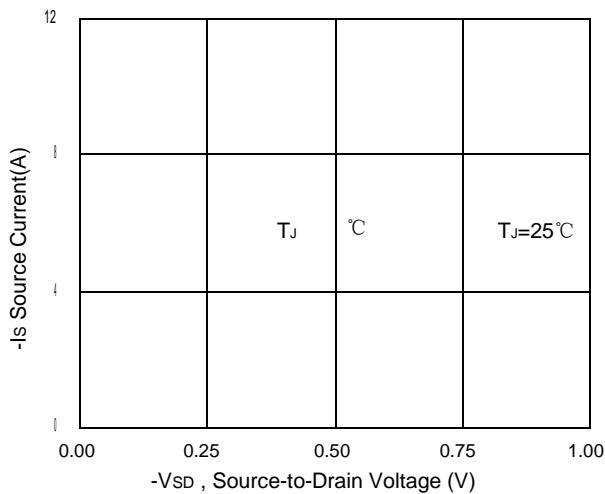


Fig.3 Forward Characteristics of Reverse

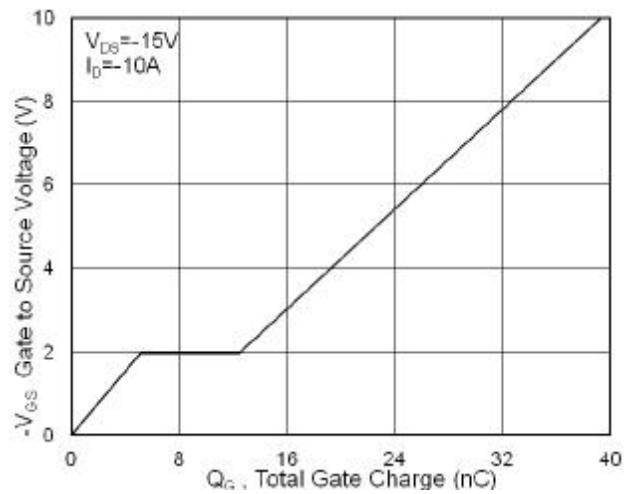


Fig.4 Gate-charge Characteristics

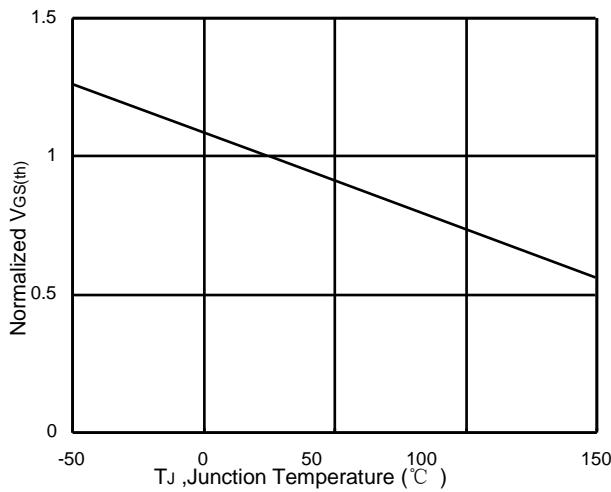


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

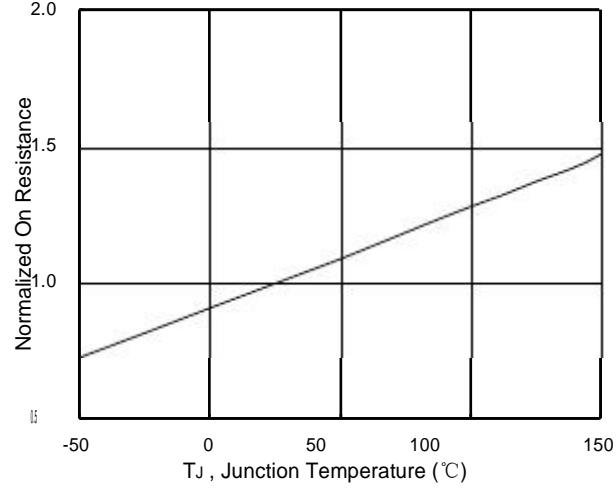


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

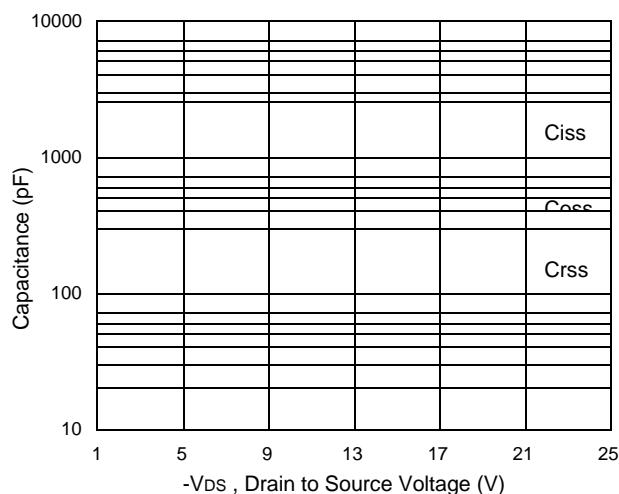


Fig.7 Capacitance

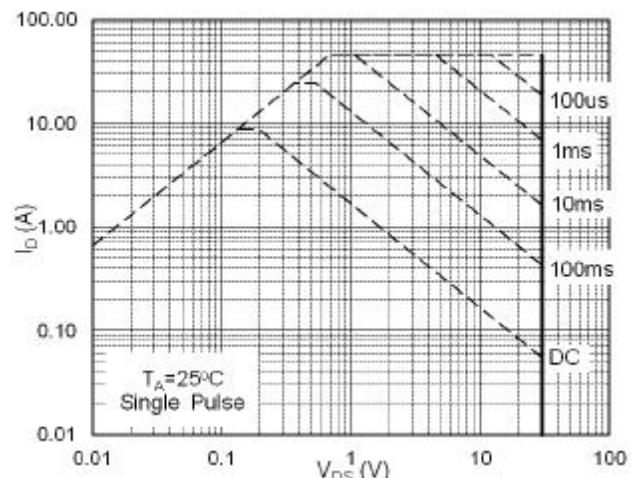


Fig.8 Safe Operating Area

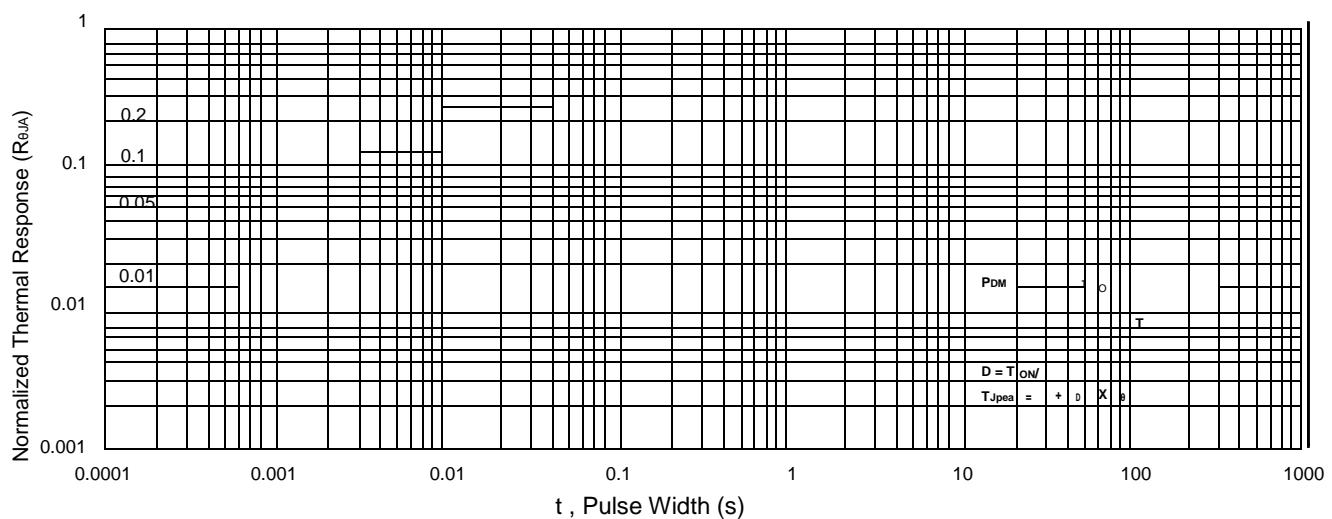


Fig.9 Normalized Maximum Transient Thermal Impedance

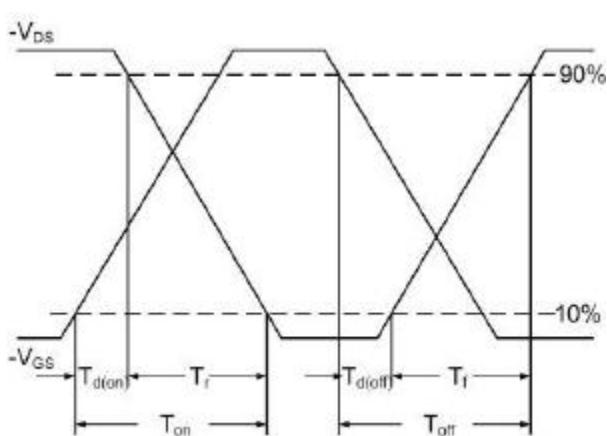


Fig.10 Switching Time Waveform

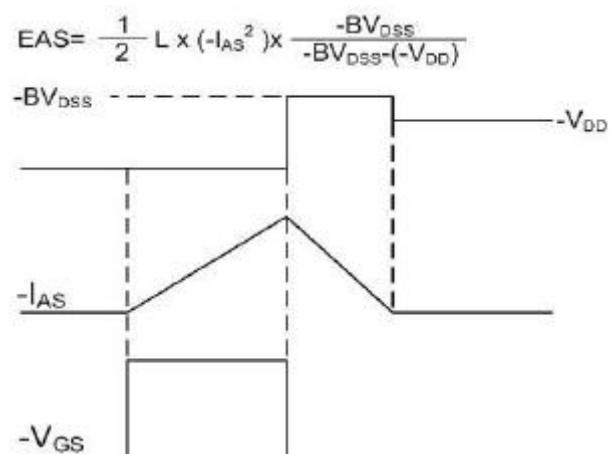
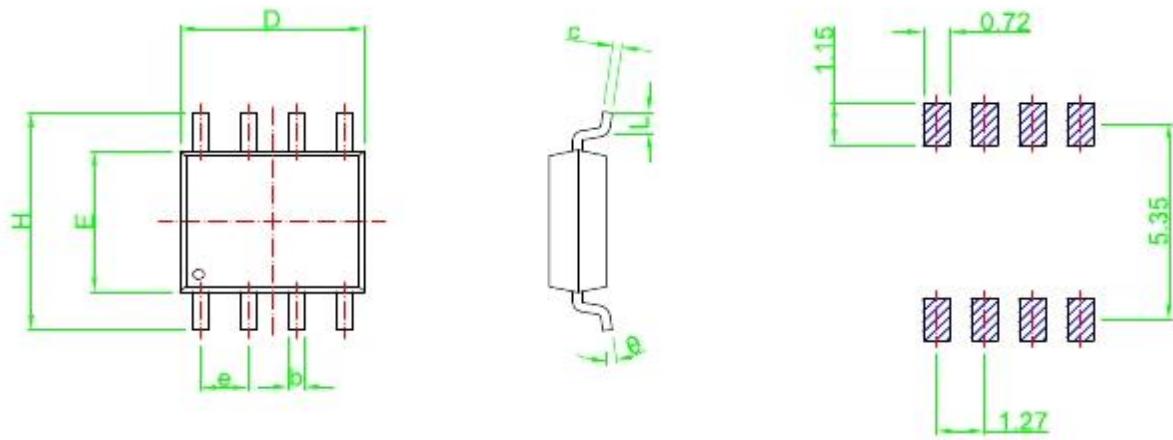
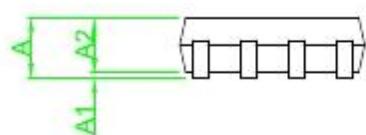


Fig.11 Unclamped Inductive Waveform



Recommended Land Pattern



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	---	1.75	---	0.069
A1	0.00	0.26	0.000	0.010
A2	1.30	1.70	0.051	0.067
b	0.30	0.55	0.012	0.022
C	0.15	0.35	0.006	0.014
D	4.80	5.00	0.189	0.197
E	3.80	4.00	0.150	0.157
e	1.27 TYP		0.050 TYP	
H	5.70	6.30	0.224	0.248
L	0.45	0.85	0.018	0.033
θ	0°	8°	0°	8°

 XIN FEI HONG	SHEN ZHEN XIN FEI HONG ELECTRONICS CO.,LTD	TITLE SOP-8	SCALE
			5 : 1
		SHEET	1 of 1
		mm THIRD ANGLE PROJECTION	